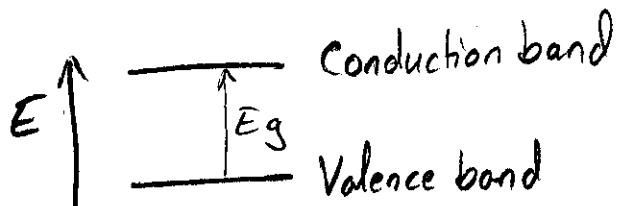


Solid-State physics

Semiconductor materials

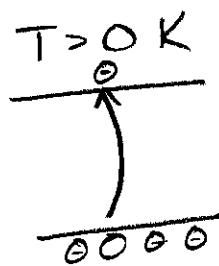
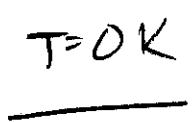
= Materials with conductivity between metals and isolators

= Bandgap $E_g \sim 0.3 - 4 \text{ eV}$



) = At absolute zero temp $T=0\text{K}$ all electrons are located in the valence band = Isolator.

) = $T > 0\text{K}$ a fraction of the electrons are ionized - conductivity > 0



) = Elemental (IV)

Si, Ge

= IV-compound

SiC, SiGe

= III-V compounds

GaAs, GaN, InP

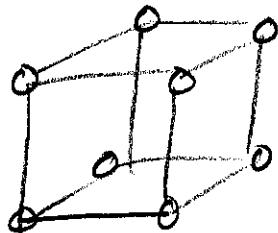
= II-VI compounds

ZnSe, CdTe

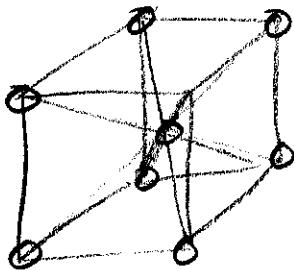
= Mostly Crystalline structure

= Amorphous and polycrystalline materials can sometimes be used as semi-conductors with bad performance.

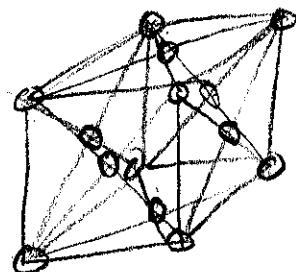
Lattices



Simple cubic
SC



Body centered cubic
BCC



Face centered cubic
FCC

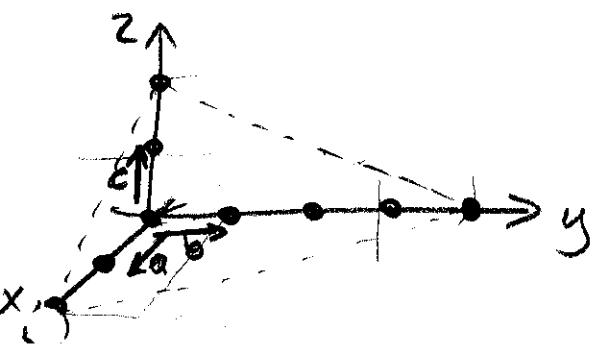
Electronic grade Si (EGS)

Impurities: parts per billion $1 \cdot 10^{-12}$

Single crystal ingots of 140 kg sliced into wafers

Plane and directions

Basis vector a, b, c



Plane intercepts the crystal axis at

$$2a, 4b, 2c$$

$$\text{reciprocals } \frac{1}{2}, \frac{1}{4}, \frac{1}{2}$$

Multiply with least common multiple

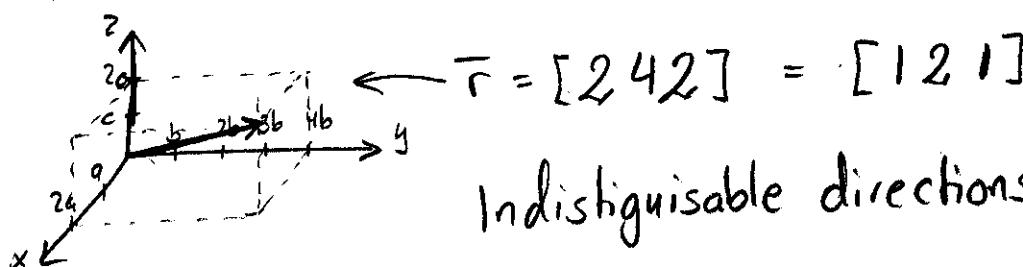
$$\times 4 \Rightarrow 212$$

Plane is labeled in brackets (212)

With symmetrical crystal axis many planes are indistinguishable

$$(100), (010), (001) \Rightarrow \{100\}$$

Direction is labelled with $[]$ and expressed in the basis vectors



Indistinguishable directions are labelled with $\langle \rangle$

$$[100], [010], [001] \Rightarrow \langle 100 \rangle$$

In cubic symmetry

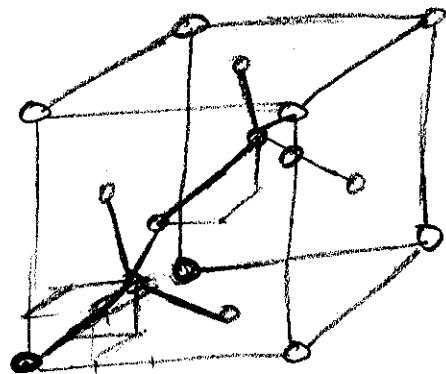
Direction $[hkl] \perp$ Plane (hkl) !!!

W45min

Diamond lattice

Lattice structure for many important semiconductors such as Si and Ge.

-) \Rightarrow FCC
 \Rightarrow Additional atom at $\frac{a}{4} + \frac{b}{4} + \frac{c}{4}$



If the additional atoms are different from the original
 \Rightarrow zincblende (GaAs)

Silicon

-) Electronic grade silicon (EGS)

Impurities: parts per billion $1 \cdot 10^{-9}$

Single crystal ingots of 140 kg sliced into wafers.
Commonly sliced in the $\{100\}$ plane

$\{111\}$ Silicon is also used

Czochralski is the most commonly used growth technique
Float zone is also common in detector applications.

Atoms and Electrons (Important, must be understood)

⇒ Electromagnetic waves (Radio, Microwave, IR, visible light, UV, X and γ -Ray) are all quantified into photons!!

$$\underline{\underline{E = \frac{h \cdot c}{\lambda}}}$$

⇒ Energy levels in atoms and crystals are discretized with a limited number of states in each level.

- Electrons moving from a higher to a lower free energy level emits a photon with

$$\lambda = \frac{h \cdot c}{E_{\text{diff}}}$$

- A photon can be absorbed in the material and excite an electron if there exist a free state with the exact energy.

$$E = E_0 + \frac{hc}{\lambda}$$

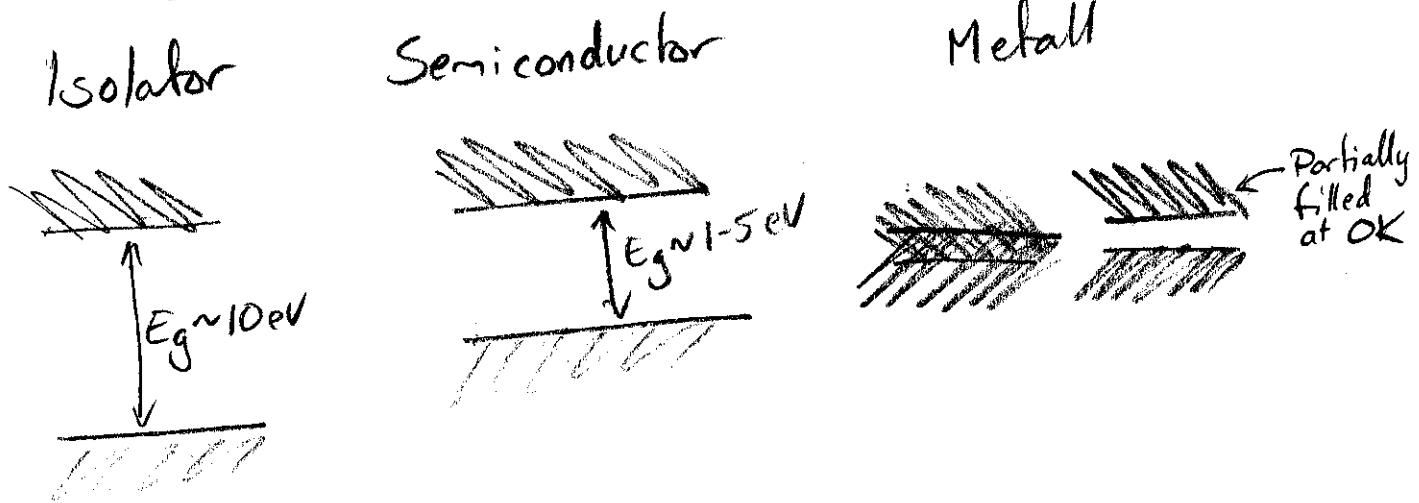
⇒ Quantum well
In a sufficiently narrow potential barrier ($L < 20 \text{ nm}$)
the allowed energy states becomes quantified

⇒ Tunneling
There is a small probability that an electron is on the opposite side of a barrier
Carrier can "tunnel through" a thin energy barrier



left I

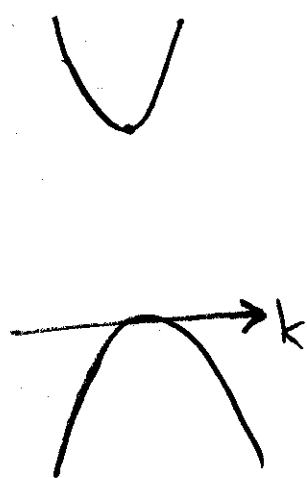
Energy bands and charge carriers



K-space (Momentum space)

Mathematically the Fourier transformation of the real space.

Energy bands in k-space are parabolic



- An electron in the bottom of the band is in rest
 - The electron velocity is proportional to the gradient
- $$V = \frac{1}{\hbar} \frac{\partial E}{\partial k}$$
- When an electrical field is applied the carriers moves with constant velocity in k-space

→ Parabolic bands $E(k) \propto k^2$
 → Accelerating in real space

- Carrier momentum

$$p = m \cdot v = \hbar k$$

classic energy

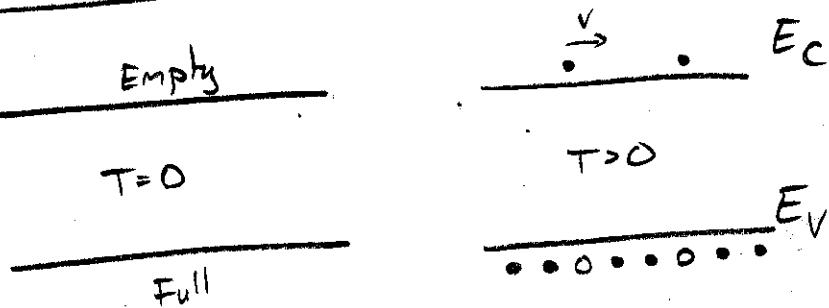
$$E = \frac{1}{2}mv^2 = /mv=p=\hbar k/ = \frac{1}{2} \frac{\hbar^2 k^2}{m}$$

$$\frac{\partial E}{\partial k} = \frac{\hbar^2 k}{m} \quad \frac{\partial^2 E}{\partial k^2} = \frac{\hbar^2}{m}$$

An effective mass, m^* can be extracted from the curvature of Energy bands in k -space

$$m^* = \frac{\hbar^2}{\frac{\partial^2 E}{\partial k^2}}$$

Electrons and holes



At temperatures above $T=0$ some electrons in the valence band is thermally excited to the conduction band. The vacancies that are created in the valence band is called "holes".

- The electrons in the conduction band are movable as plenty of nearby free states exists.

- Electrons in the valence band can move to the vacancy created by the hole

- This is equivalent to saying that the hole is moving in the opposite direction.

$$\begin{array}{c} \bullet \bullet \bullet \\ \text{Ev} \\ \bullet \bullet \bullet \end{array}$$

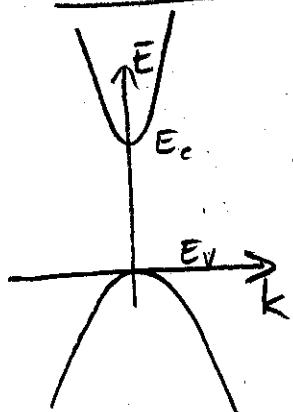
- The effective mass for holes is often lower than for electrons as it requires many electrons to participate in the transport.

- Excited electrons and holes are always created in pairs.

- In room temperature

$$N_i \sim 10^{10} \text{ cm}^{-3} \quad N_{Si} \sim 5 \cdot 10^{22} \text{ cm}^{-3}$$

Direct, indirect bandgap



Materials where the conduction band minima and valence band maxima coincides in k -space are called direct bandgap.

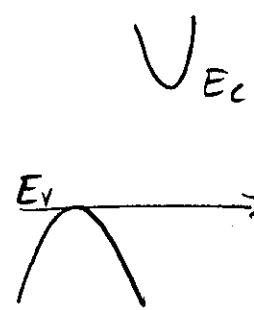
Between the two states electrons can excite and deexcite interacting with just a photon



- Very important in optical devices such as lasers and LEDs (Light emitting diodes)

Materials: GaAs, GaN, InP





In SP $E_{v\text{-max}}$ and $E_{c\text{-min}}$ occurs at different \mathbf{k} -vectors.

A transition between the two bands requires a change in momentum for the electron.

As photons are mass-less ($p=0$) the momentum change must come from some other transition

- Phonons (Lattice vibrations)
- Defect levels

Intrinsic materials

- Perfect semiconductor without any impurities
- electron conc = hole conc = intrinsic conc

$$n = p = n_i$$

(Temperature dependent according to Fermi-Dirac statistics)

Generation rate = Recombination rate

$$g_i = r_i \quad (\text{Temp dependent})$$

Extrinsic materials

- Carrier can also be created intentionally by doping
 - During growth
 - Implantation
 - Diffusion

- By adding an impurity with just 3 valence electrons doping level is created just above E_V .

- The doping level easily accepts an valence electron and leaves a hole in the valence band $\longrightarrow E_C$
- Acceptor level
- B, Al, Ga, In $E_A \longrightarrow E_V$

- Impurity from group IV P, As, Sb $E_D \longrightarrow E_C$

- Doping energy just below E_C
- Donates its electron to the conduction band, donor level.

Carrier concentration

Electrons in solids obey Fermi-Dirac statistics

$$f(E) = \frac{1}{1 + e^{(E - E_F)/kT}}$$

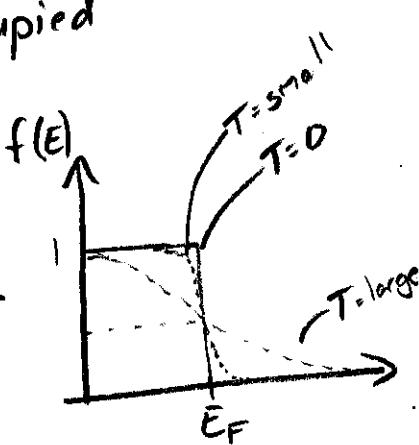
k - Boltzmann's const

T - Temp in K

E_F - Fermi energy level

$f(E)$ - Probability that an state is occupied

$$f(E_F) = \frac{1}{1 + e^{(E_F - E_F)/kT}} = \frac{1}{1 + e^0} = \frac{1}{1+1} = \frac{1}{2}$$



ReP

Photon energy

$$E = \frac{hc}{\lambda}$$

Direct bandgap mtrl emits photons with

$$\lambda = \frac{hc}{E_g}$$

All semiconductor mtrl absorbs photons with

$$\lambda \leq \frac{hc}{E_g}$$

The electron velocity is proportional to the gradient of the energy bands in k-space

$$v = \frac{1}{\hbar} \frac{\partial E}{\partial k}$$

Effective mass is proportional to the curvature of the bands

$$m^* = \frac{\hbar^2}{\frac{\partial^2 E}{\partial k^2}}$$

Fermi-Dirac distribution

$$f(E) = \frac{1}{1 + e^{(E - E_F)/kT}}$$

Density of states

Cone in conduction band

$$n_0 = \int_{E_0}^{\infty} f(E) N(E) dE$$

3-12

Equilibrium

$N(E)$ - Density of states

To simplify calculations an effective density of states (N_c, N_v) is defined located at the band edge

$$n_0 = N_c \cdot f(E_c)$$

3-13

For holes

$$p_0 = N_v \cdot (1 - f(E))$$

3-17

For intrinsic material

E_F close to middle of bandgap

$$f(E) = \frac{1}{1 + e^{-(E-E_F)/kT}} \approx e^{-(E-E_F)/kT}$$

$$n_i^0 = N_c e^{-\frac{E_c - E_i^0}{kT}} \quad p_i^0 = N_v e^{-\frac{E_v^0 - E_i^0}{kT}}$$

$$n_i^0 p_i^0 = N_c \cdot N_v e^{-\frac{(E_c - E_v^0)}{kT}} = N_c \cdot N_v e^{-E_g/kT}$$

$$n_i^0 = p_i^0 \quad (\text{created in pairs})$$

$$n_i^0 = \sqrt{N_c \cdot N_v} e^{-\frac{E_g}{2kT}}$$

3-23

As long as the fermilevel is a few kT ($\sim 26\text{meV}$) away from valence and conduction band the simplification of $f(E)$ is correct

$$f(E) = e^{-(E-E_F)/kT}$$

$n_0 p_0$ can be calculated as above

$$n_0 p_0 = N_c N_v e^{-E_g/kT}$$

3-22a

$$\underline{n_0 p_0 = n_i^2}$$

3-24

$$n_0 = N_c e^{-(E_C-E_F)/kT} = n_i^2 e^{(E_C-E_i^2)/kT} e^{-(E_C-E_F)/kT}$$

$$n_0 = n_i^2 e^{(E_F-E_i^2)/kT}$$

3-25a

$$P_0 = n_i^2 e^{(E_i - E_F)/kT}$$

3-25b

Carrier concentration is very temperature dependent

In Fig 3-17 $T=300 \rightarrow 400\text{K}$, $n_i^2 = 10^{10} \rightarrow 10^{13} \text{ cm}^{-3}$

- In the presence of both acceptor and donor doping the majority concentration determines the final doping.
- For electrostatic neutral material the free carriers must balance the ionized doping atoms

$$P_0 + N_d^+ = n_0 + N_a^-$$

If $n_0 \gg P_0$

$$n_0 \approx N_d - N_a$$

The carriers moves randomly like gas molecules

\Rightarrow Diffusion Higher conc \rightarrow Lower conc

The carriers are affected by electric and magnetic fields

\Rightarrow Drift

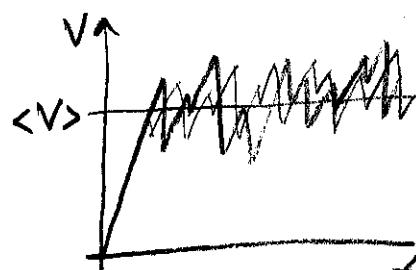
- Accelerated by the field
- Scattered against the lattice and other carriers
- Equilibrium mean velocity $\langle v \rangle$

Mobility M

$$M = -\frac{\langle v \rangle}{E} \quad \frac{cm^2}{Vs}$$

Current density

$$J = q \cdot n \cdot M \cdot E$$



Both electrons and holes

$$J = q(n \cdot \mu_n + p \cdot \mu_p) E = \sigma E$$

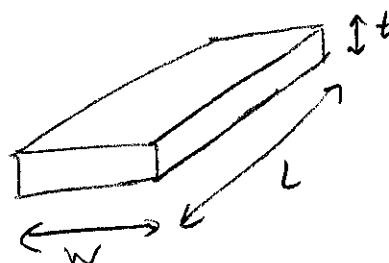
σ - conductivity

$$\sigma = q(n\mu_n \cdot p\mu_p) = \frac{1}{\rho}$$

ρ - Resistivity

Resistance

$$R = \frac{\rho L}{w t} = \frac{L}{w t} \frac{1}{\sigma}$$



The mobility is not constant

- Decreases with doping concentration Fig 3-23

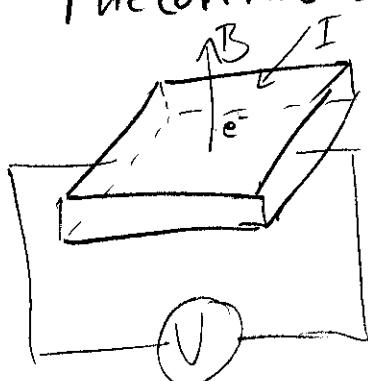
- Decreases at high temperatures Fig 3-22

- Decreases at high electrical fields

→ The mean velocity saturates Fig 3-24 Lect 3

Hall effect

The carriers are affected by a magnetic field



$$F = q(E + v \times B)$$

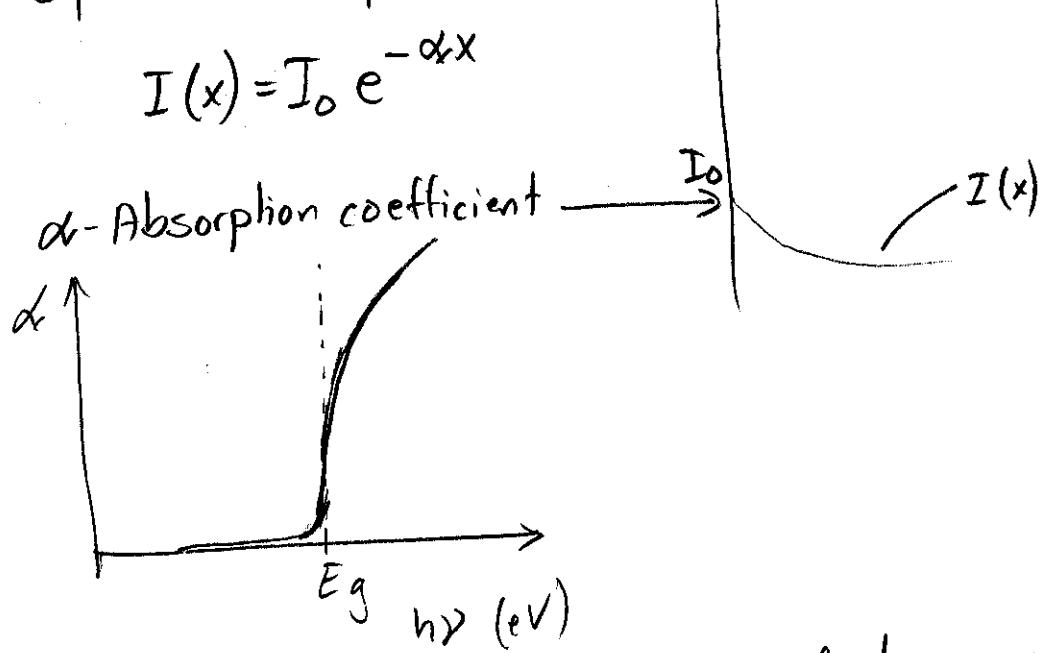
$$F_y = qE_y - qvB_z$$

- Carriers moves in the y-direction
- A Voltage are built up \rightarrow generates a Electrical counter-field to the magnetic field
- Stationary condition.

Excess Carriers in Semiconductors

- Carriers in excess of thermal equilibrium values
- Optical excitation
- Electron bombardment
- Injection in p-n junction diodes

Optical absorption



α - Energy or wavelength dependent $\lambda = \frac{hc}{Eg}$
 Semiconductor material transparent below bondgap.

Photoconductivity

⇒ Optical luminescence

→ Generates excess electrons and holes

→ Increased conductivity

Direct recombination

Excess electrons falls back to the valence band spontaneously.

Energy is given up as a photon with energy

$$\hbar\nu \approx E_g$$

Decay rate proportional to # electrons and # holes
 $\propto r_r \cdot n(t)p(t)$

Net change in carrier conc

$$\frac{dn(t)}{dt} = \underbrace{dr_r n_i^2}_{\text{Thermal generation rate}} - \underbrace{dr_r n(t)p(t)}_{\text{Recombination}}$$

In excess carriers

$$\begin{aligned} \frac{d\delta n(t)}{dt} &= dr_r n_i^2 - dr_r (n_0 + \delta n(t)) (p_0 + \delta p(t)) = \\ &= \cancel{dr_r n_i^2} - dr_r (\cancel{n_0 p_0} + n_0 \delta p(t) + p_0 \delta n(t) + \delta n(t) \delta p(t)) = \\ &= -dr_r (n_0 + p_0) \delta n(t) + \delta n^2(t) \end{aligned}$$

neglect as $\delta n(t)$
is small

In p-type material

$$\frac{d\Delta n(t)}{dt} = -dr_P \rho_0 \Delta n(t)$$

$$\Delta n(t) = \Delta n e^{-dr_P \rho_0 t} = \Delta n e^{-t/\tau_n}$$

↑
Original excess conc

τ_n - Recombination lifetime
 $\tau_n = \frac{1}{dr_P \rho_0}$

In n-type material

$$\tau_p = \frac{1}{dr_n n_0}$$

Indirect recombination

In semiconductors with indirect bandgap such as Silicon or Germanium falls back via recombination levels in the band-gap
 \Rightarrow Energy is given to the lattice as heat.

Impurities and lattice defect can act as trapping center if an electron or hole can be captured and subsequently be annihilated by an opposite carrier type.

If the opposite carrier isn't trapped soon enough the trapped carrier may be thermally reexcited again.

Indirect recombination is much more difficult analyzing than direct.

Steady-state carrier generation

In many problems a steady state carrier generation is maintained

$$\frac{\partial}{\partial t} = 0$$

$$\frac{d^2 \delta n}{dx^2} = \frac{\delta n}{D_n \tau_n} \equiv \frac{\delta n}{L_n^2}$$

— Diffusion length
Represents the length where the conc is reduced to $1/e$

- A simple fermi level is not meaningful ~~at all~~ in presence of excess carriers.

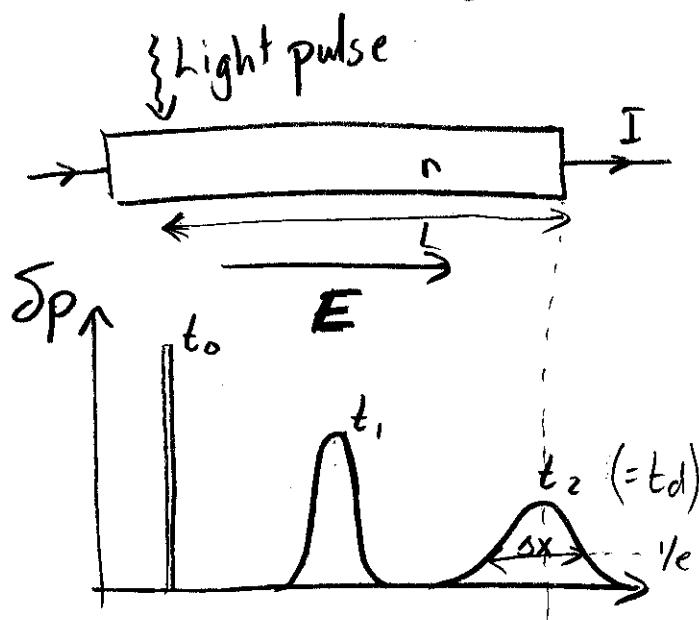
By defining separate quasi-fermi levels carrier conc eq like 3-25 can be achieved

$$n = n_i^2 e^{(F_n - E_i)/kT}$$

$$p = n_i^2 e^{(E_i - F_p)/kT}$$

F_n and F_p electron and hole quasi-fermi levels

Haynes-Shockley experiment



By measuring the current at the right contact
the mobility and Diffusio coefficient can be
measured simultaniously

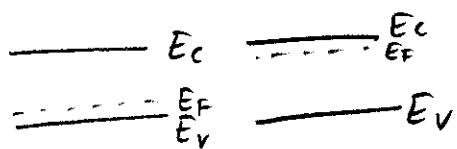
$$M_P = \frac{V_d}{E} = \frac{L}{t_d \cdot E}$$

$$D_P = \frac{(\Delta x)^2}{16 t_d} \quad (\text{Details in book})$$

M_P and D_P should fulfill einsteins relation

$$\frac{D_P}{M_P} = \frac{kT}{q}$$

Junctions



Bring together

- Diffusion of holes $p \rightarrow n$
electrons $n \rightarrow p$

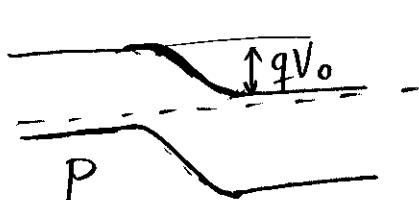
→ elec. and holes meet and recombine

Fixed doping charges build up an electrical field

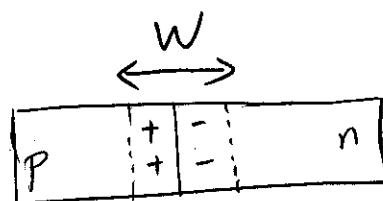
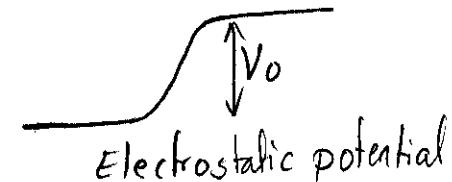
→ Drift current which exactly cancels the diffusion current

→ No net current at equilibrium

Fermi level is constant at equilibrium



Energy bands



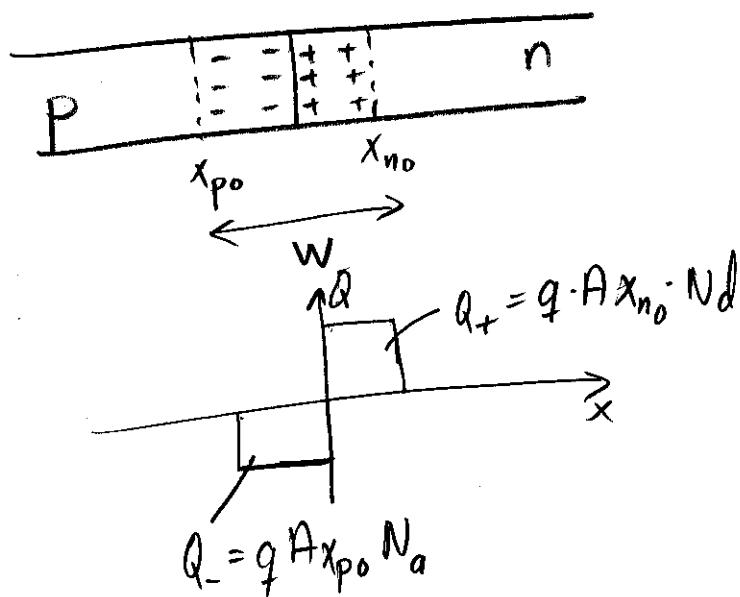
W - Space charge region

Built in potential, V_0 (Contact potential)

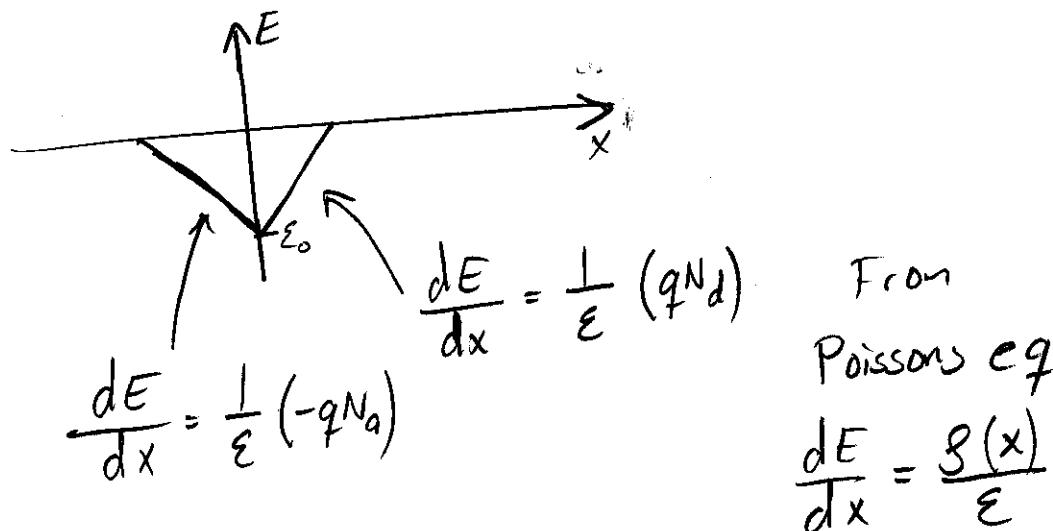
- Cannot be measured by just adding probes
- Additional contact potentials are created at the probes cancelling $\cdot V_0$

Lect 4
↓↓

Space charge



$$Q_+ = Q_- \Rightarrow x_{no} N_d = x_{po} N_a$$



The maximal electrical field

$$E_0 = -\frac{q}{\epsilon} N_d x_{n_0} = -\frac{q}{\epsilon} N_a x_{p_0}$$

Contact potential

$$-V_0 = \int_{-x_{p_0}}^{x_{n_0}} E(x) dx = / \text{triangle} / = \frac{1}{2} E_0 W$$

$$V_0 = -\frac{1}{2} \frac{q}{\epsilon} N_d x_{n_0} \cdot W$$

$$x_{n_0} = x_{p_0} \frac{N_a}{N_d} = (W - x_{n_0}) \frac{N_a}{N_d} = W \frac{N_a}{N_d} - x_{n_0} \frac{N_a}{N_d}$$

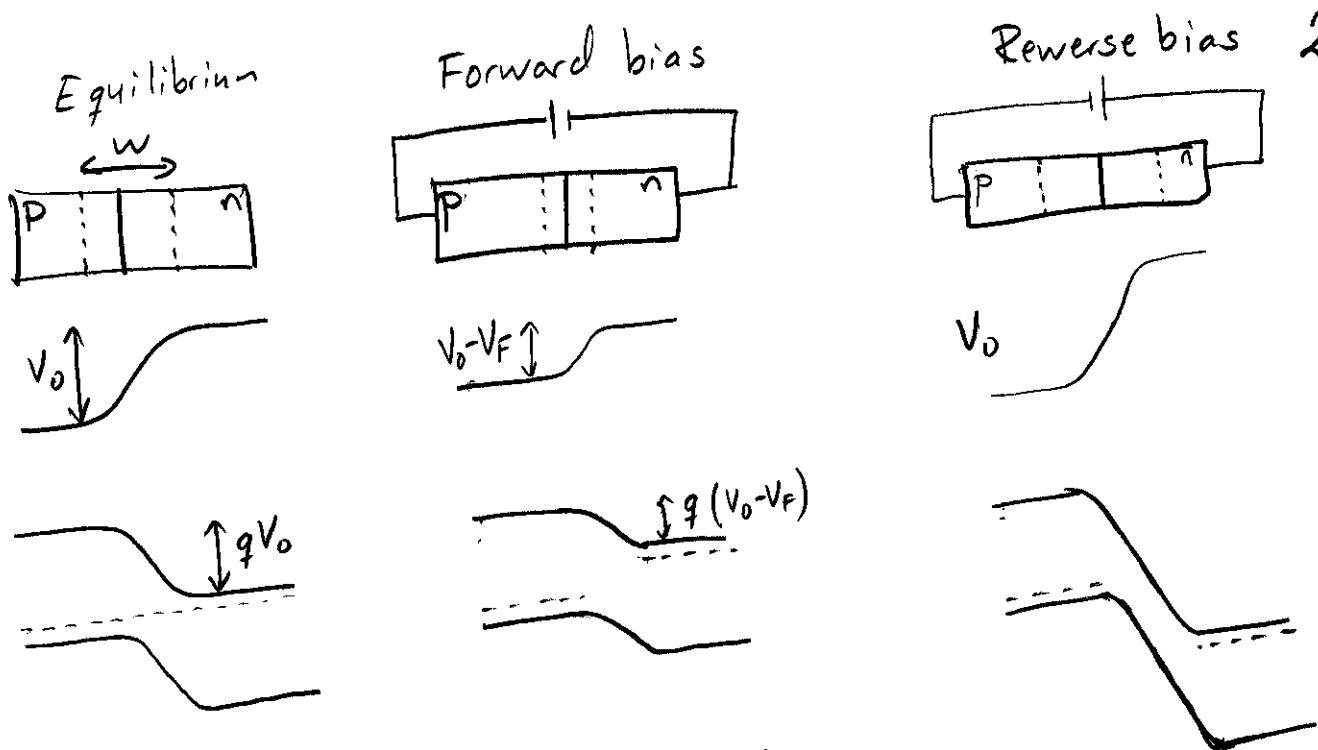
$$\Rightarrow x_{n_0} \left(1 + \frac{N_a}{N_d}\right) = W \frac{N_a}{N_d} \quad x_{n_0} = \frac{W N_a}{N_d \left(1 + \frac{N_a}{N_d}\right)} = \frac{W N_a}{N_d + N_a}$$

$$V_0 = -\frac{1}{2} \frac{q}{\epsilon} \frac{N_a N_d}{N_a + N_d} W^2$$

$$W = \sqrt{\frac{2 \epsilon V_0}{q} \left(\frac{N_a + N_d}{N_a N_d} \right)}$$

~~+~~

Junction capacitance $C = \frac{\epsilon \cdot A}{W}$ Parallel plate formula



Reduced depletion

\Rightarrow Diffusion current increases

\Rightarrow Diffusion current reduced

EHP:s are constantly thermally and optically generated.

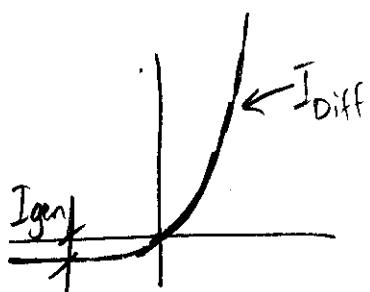
EHP:s in the depletion region drifts in the field.

\Rightarrow Generation current (Drift current)

\Rightarrow Rather insensitive to the potential barrier (E-field). It's the number of carriers that determines the current not the velocity.

At equilibrium the diffusion and generation current cancels.

$$I = I_{\text{diff}} - |I_{\text{gen}}| = 0 \text{ for } V=0$$



The probability for a carrier to diffuse across the junction increases exponentially

$$\Rightarrow I = I_0 \left(e^{\frac{qV}{kT}} - 1 \right)$$

The drift and diffusion current must cancel at equilibrium

$$J_p(x) = q \left(M_p P(x) E(x) - D_p \frac{dP(x)}{dx} \right) = 0$$

$$\frac{M_p}{D_p} E(x) = \frac{1}{P(x)} \frac{dP(x)}{dx}$$

$\underbrace{\frac{q}{kT}}$ $\frac{dV}{dx}$

$\frac{q}{kT}$ = Einstein's relation

$$-\frac{q}{kT} \frac{dV}{dx} = \frac{1}{P(x)} \frac{dP(x)}{dx}$$

$$-\frac{q}{kT} \int_{V_p}^{V_n} dV = \int_{P_p}^{P_n} \frac{1}{P} dP$$

$$-\frac{q}{kT} \underbrace{(V_n - V_p)}_{V_0} = \ln P_n - \ln P_p$$

$$V_0 = \frac{kT}{q} \ln \frac{P_p}{P_n}$$

$$\frac{P_p}{P_n} = e^{\frac{qV_0}{kT}} \quad (= \frac{n_n}{n_p})$$

5.10

\uparrow Equilibrium values

Applying bias

$$\frac{P(-x_{p0})}{P(x_{n0})} = e^{\frac{q(V_0 - V)}{kT}} \simeq \frac{P_p}{P(x_{n0})}$$

Majority carrier is approx constant under low injection

\uparrow
Non equilibrium

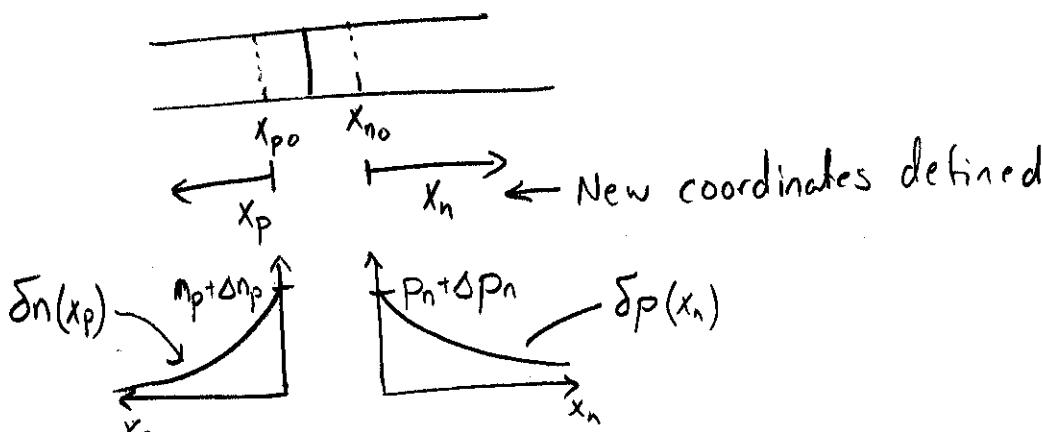
$$\frac{P_p/p_n}{P_p/p(x_{n0})} = \frac{e^{\frac{qV_0}{kT}}}{e^{\frac{q(V_0-V)}{kT}}}$$

$$\frac{P(x_{n0})}{P_n} = e^{\frac{qV}{kT}}$$

Excess conc at the edge of the transition region

$$\Delta P_n = P(x_{n0}) - P_n = P_n (e^{\frac{qV}{kT}} - 1)$$

$$\Delta n_p = n_p (e^{\frac{qV}{kT}} - 1)$$



Assuming long $\frac{n}{\Delta n(x_p)}$ region:

$$\frac{\Delta n(x_p)}{\Delta n(x_p)} = \Delta n_p e^{-x_p/L_n} = n_p (e^{qV/kT} - 1) e^{-x_p/L_n}$$

$$\Delta P(x_n) = \Delta P_n e^{-x_n/L_p} = P_n (e^{qV/kT} - 1) e^{-x_n/L_p}$$

Hole diffusion current

$$\begin{aligned} I_p(x_n) &= -qA D_p \frac{d\Delta P(x_n)}{dx_n} = qA \frac{D_p}{L_p} \Delta P_n e^{-x_n/L_p} \\ &= qA \frac{D_p}{L_p} \Delta P(x_n) \end{aligned}$$

Hole current injection

$$I_p(x_n=0) = \frac{qAD_p}{L_p} p_n (e^{qV/kT} - 1)$$

elec inj.

$$I_n(x_p=0) = -\frac{qAD_n}{L_n} n_p (e^{qV/kT} - 1)$$

↑
- x_p direction

Total current

$$\underline{I = qA \left(\frac{D_p}{L_p} p_n + \frac{D_n}{L_n} n_p \right) (e^{qV/kT} - 1)}$$

Diode equation.

Both in forward and reverse direction

Lect 5

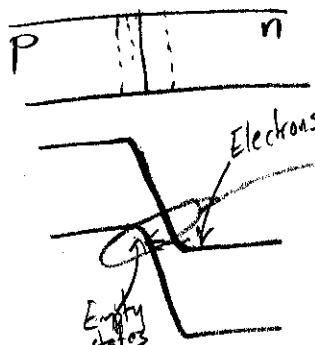


High reverse bias

Two different cases

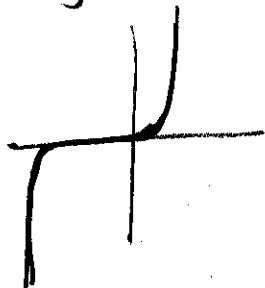
High doping

→ Thin depletion region

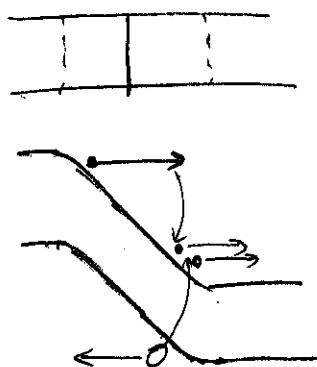


The probability of tunnelling becomes significant

⇒ Zener effect



Low doping



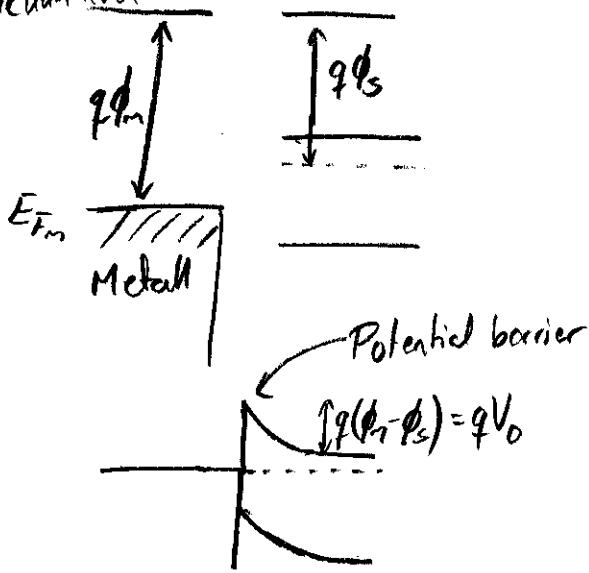
- Electron gains high energy as they drift in the field
- When the energy $> E_g$ it is sufficient to create a new electron-hole pair
- The new carriers can create even more EHP:s

\Rightarrow Avalanche effect

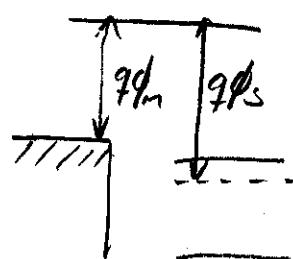
Metal - Semiconductor junctions

A metal-semiconductor junction can either be rectifying or ohmic depending on the "work-function" of the metall.

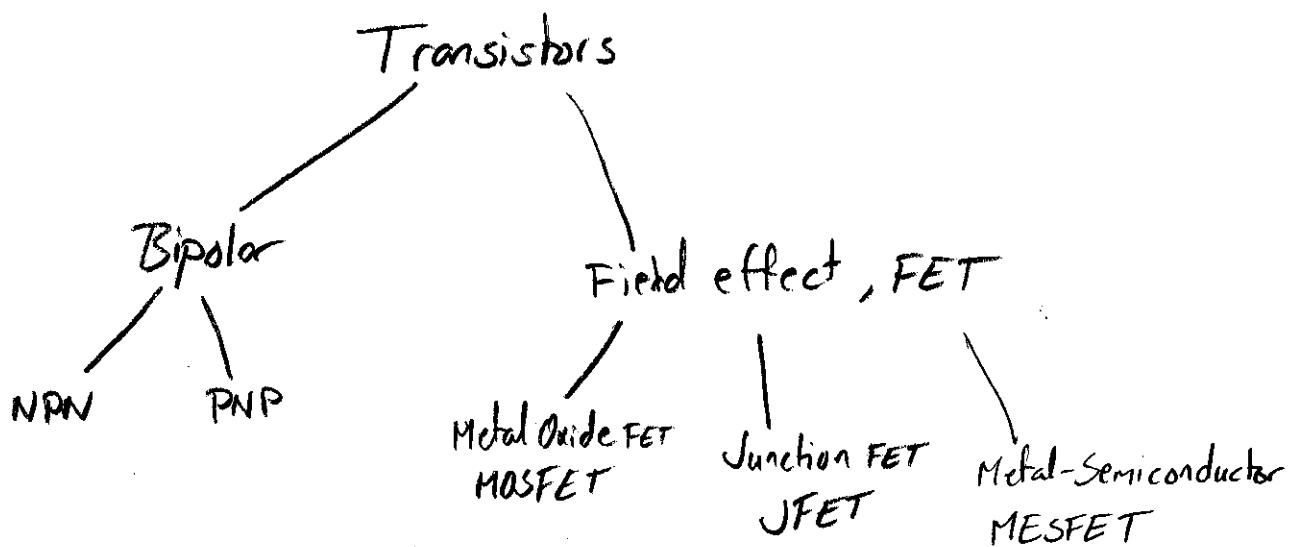
Rectifying cont.
Vacuum level



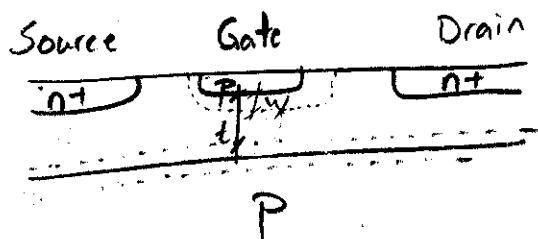
Ohmic



Transistors



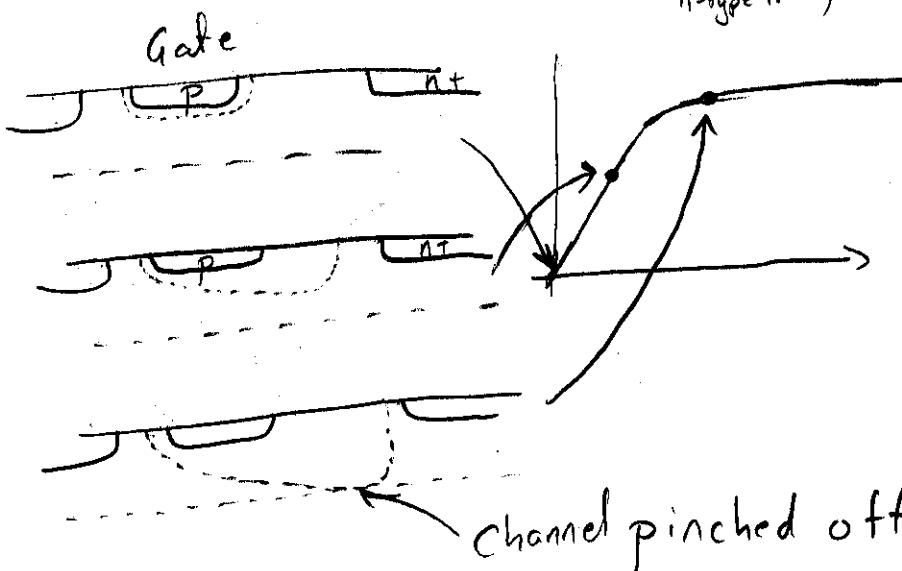
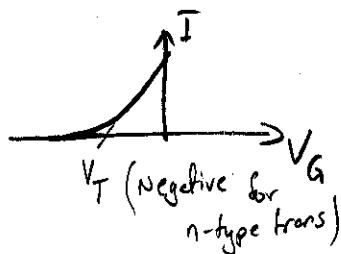
Junction FET, JFET



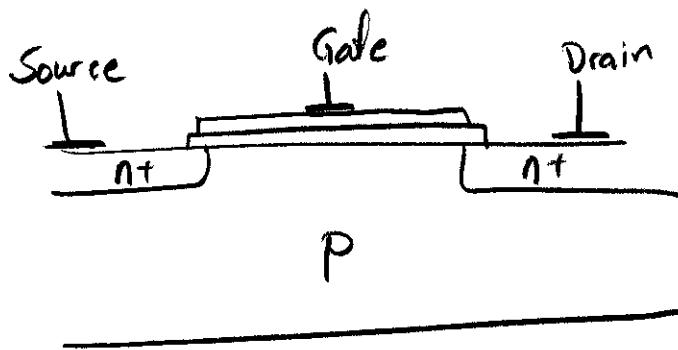
$$W = f(V_G)$$

$$I = q \eta M E \cdot A \quad \text{where } A \propto t - w$$

At $V_G = 0 \Rightarrow W = \min \Rightarrow I = \max$



Metal Insulator Semiconductor FET MISFET Oxide MOSFET



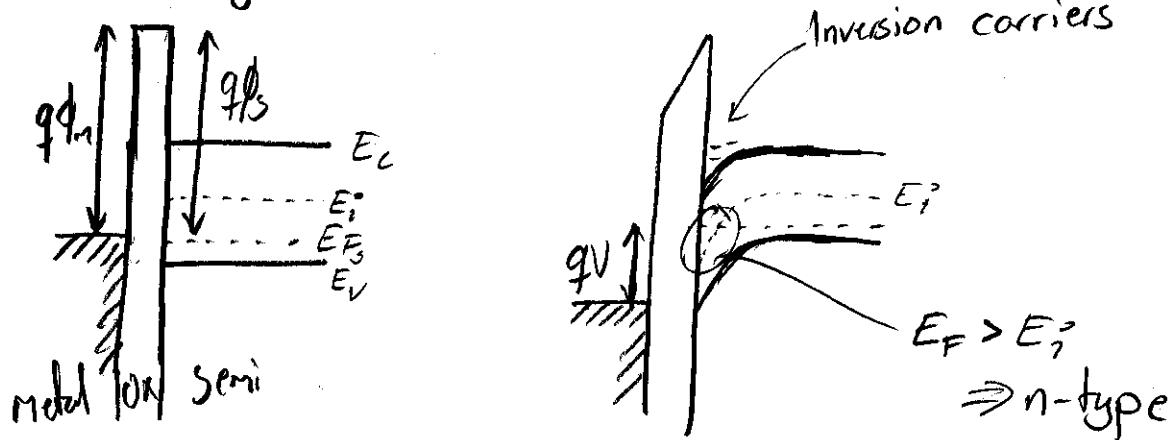
- Positive gate bias

- Depletes the holes from the surface

- Attracts electrons to the surface

\Rightarrow Inversion layer (p-mtl becomes n-conductive)

Band diagram



$$V_g = 0$$

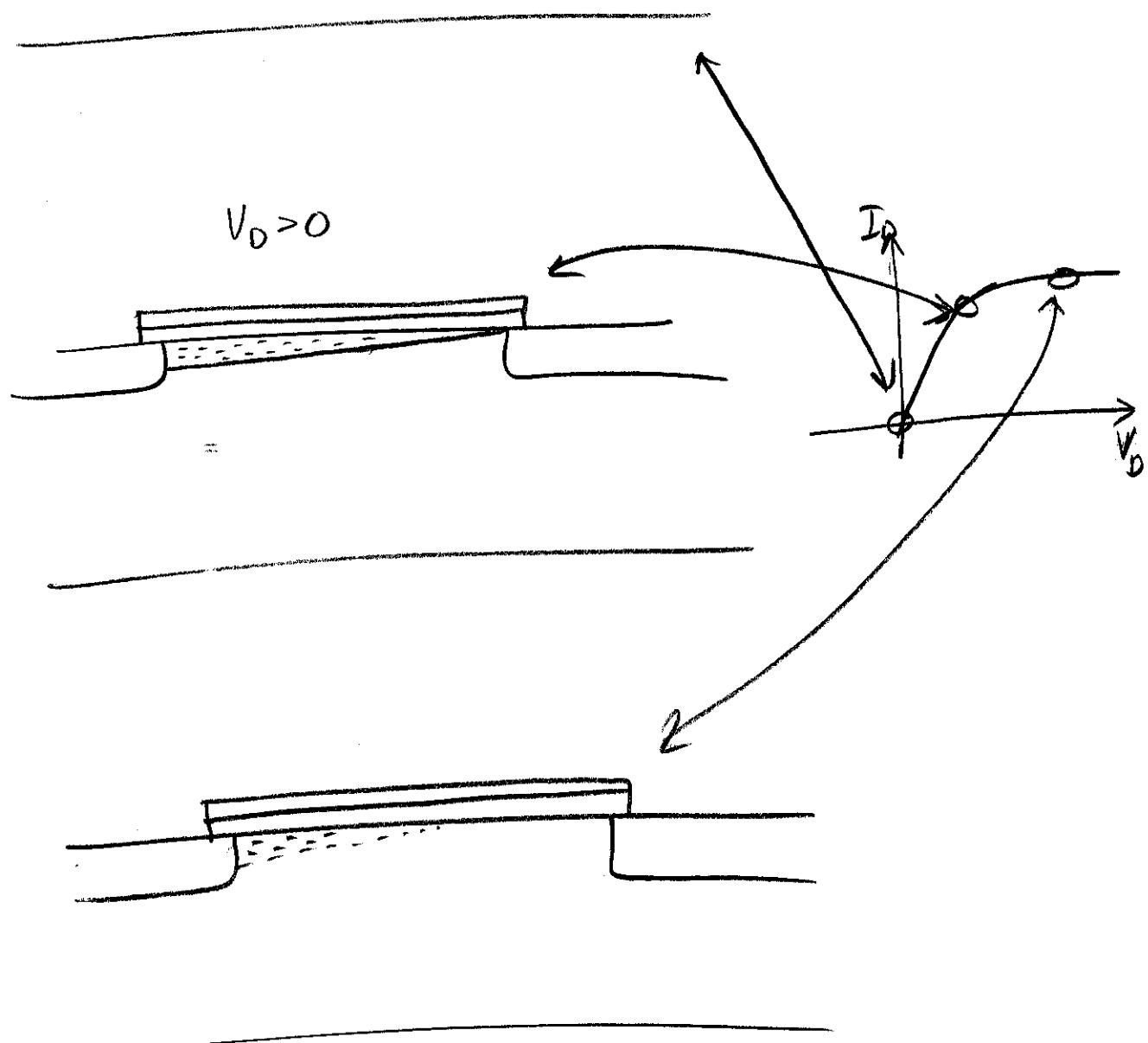
$$I_D \uparrow$$

$$V_g > 0$$



V_T positive for n-channel

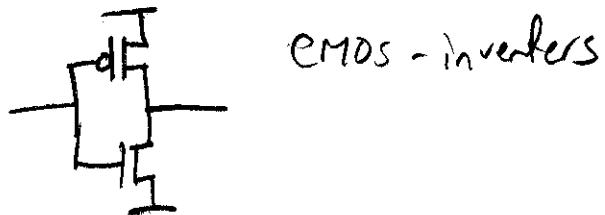
$$V_G > V_T, V_D = 0$$



MOSFETs totally dominates in digital applications

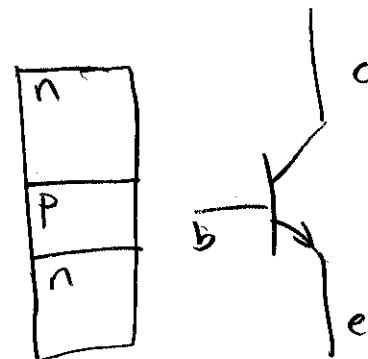
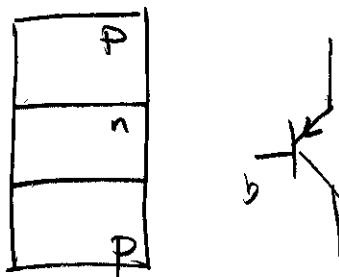
Contributing factors

- Complementary logic CMOS
nmos & pmos integrated
- Allows simple logic building blocks

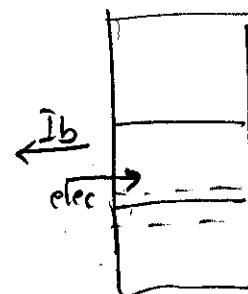
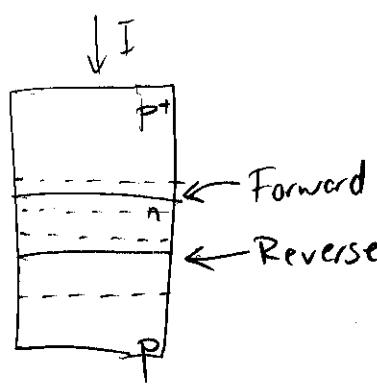


- Scaling has allowed shrunked size and improved performance
 - However, scaling cannot be continued much longer due to fundamental limitations
 - Gate leakage
 - Source-Drain leakage current

Bipolar transistor



- Two diodes coupled facing each other
- the reverse current is determined by the number of minority carriers



Electrons injected into the

- Minority carriers are injected in the base through the forward biased junction
 - Increased reverse bias
 - Small amount of injected carriers recombine in the base region
 - Must be resupplied from the base current.

Photo detector

- Reverse biased pn-junction diode

Light emitting diode

- Forward biased diode in direct bandgap material.

Semiconductor lasers

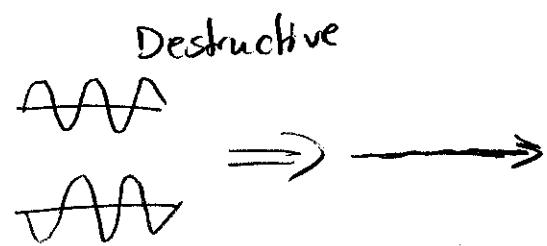
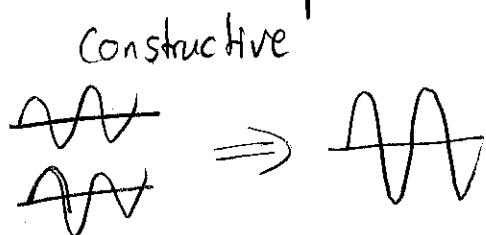
- pn-junction diode surrounded by cavity mirrors.

Optics

- Interference
- Diffraction
- Reflection in thin films
(Transfer matrix)

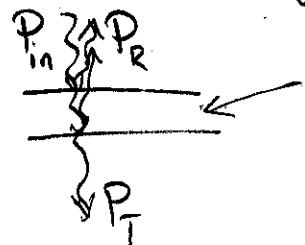
Interference

- Two waves with the same wavelength can either summarize or cancel depending on the relative phase



Interference in thin films

Two reflecting layers



Maximal transmission if the two reflected waves interfere destructively

$$P_T = P_{in} - P_R$$

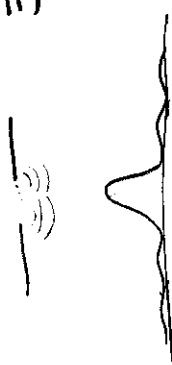
Difraction

Monochromatic ray of light passing an edge or slit is spread.

? Huygen's principle

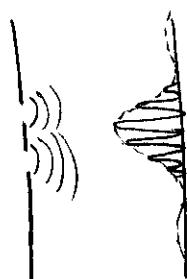
- The wave front can be replaced by multiple point sources.

Single slit



One strong interference peak and additional weak peaks

Double slit



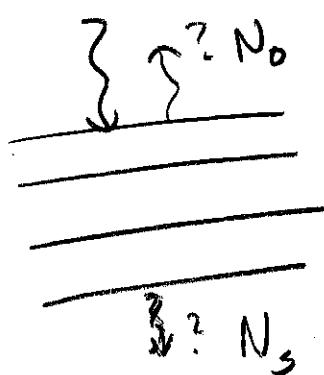
Many slits (Bragg grating)



Theory of multilayer films

3

Transmission matrix (Perpendicular incidence)



For each layer in a dielectric stack a transfer matrix can be calculated such as

$$M_x = \begin{bmatrix} \cos \ell\delta & -\frac{i}{N} \sin \ell\delta \\ -iN \sin \ell\delta & \cos \ell\delta \end{bmatrix}$$

ℓ is the layer thickness

$$\delta \equiv \frac{2\pi N}{\lambda_0} \quad \text{where } N(\lambda) = n(\lambda) + ik(\lambda)$$

Complex refractive index
including absorption

The transfer matrix can be calculated by matrix multiplication

$$M = M_1 \cdot M_2 \cdot \dots \cdot M_3 = \begin{bmatrix} A & B \\ C & D \end{bmatrix}$$

The transmission coefficient for the whole stack

$$t = \frac{2N_0}{A \cdot N_0 + N_0 \cdot N_s \cdot B + C + N_s \cdot D}$$

N_0 - Indice medium
(Air $N_0=1+i0$)
 N_s - Substrate

The transmittance

$$T = \frac{\text{Re}(N_s)}{\text{Re}(N_o)} |t|^2$$